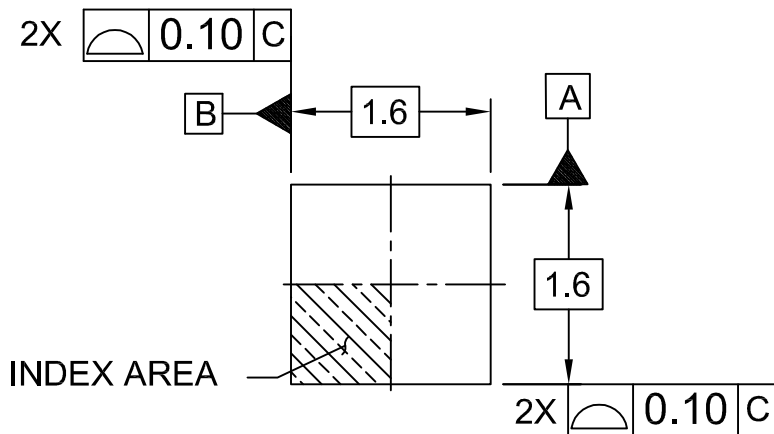
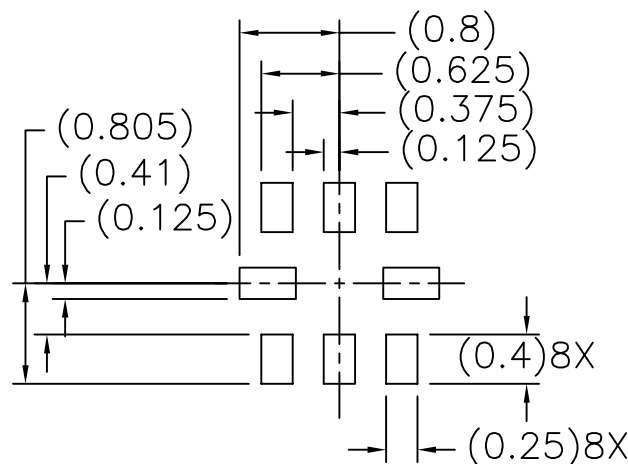


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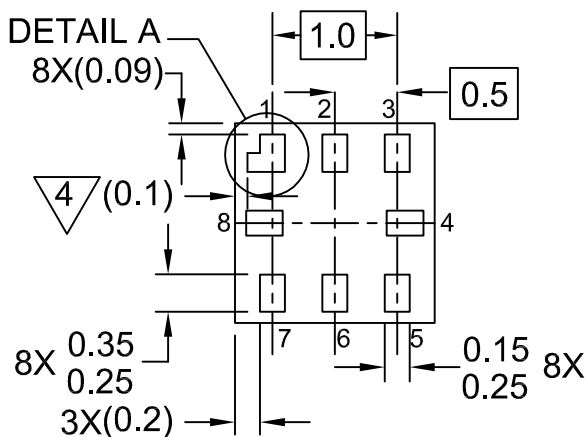
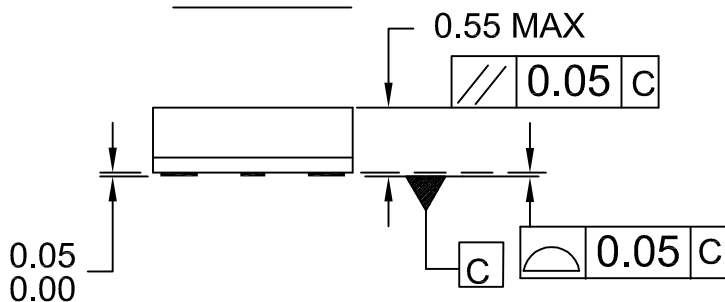
REVISIONS				
LTR	DESCRIPTION	EDCN	DATE	BY/APP'D
A	Initial Drawing Release to Doc control	ECN-MKT-MAC08A	11/26/02	H.HALLEN
B	Revised landpattern recommendation and terminal dimensions	ECN-MKT-MAC08RevB	3/28/03	H.HALLEN
C	REVISED PIN ONE INDEX AREA	ECN-MKT-MAC08RevC	11/17/04	H.HALLEN
4	ADDED IN PIN #1 TERMINAL DETAIL	ECN-MKT-MAC08Rev4	APRIL 05, 07	CHP KING



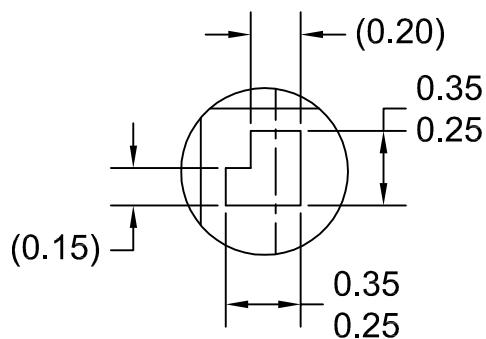
TOP VIEW



Recommended Landpattern



BOTTOM VIEW



DETAIL A
PIN #1 TERMINAL
SCALE: 2X

Notes:

1. PACKAGE CONFORMS TO JEDEC MO-255 VARIATION UAAD
2. DIMENSIONS ARE IN MILLIMETERS
3. DRAWING CONFORMS TO ASME Y.14M-1994
4. PIN 1 FLAG, END OF PACKAGE OFFSET
5. DRAWING FILE NAME: MKT-MAC08AREV4

MAC08AREV4

APPROVALS	DATE	FAIRCHILD SEMICONDUCTOR		
DRAWN: CHIP KING	09 APRIL,07	Bayan Lepas, FIZ, 11900, Penang, Malaysia.		
DFTG. CHK: GL CHEW	09 APRIL,07	8LD, MICROPAK, JEDEC MO255, VARIATION UAAD, 1.6MM SQUARE		
ENGR. CHK: DAVID CHONG	09 APRIL,07			
PROJECTION		SCALE	SIZE	DRAWING NUMBER
		N/A	N/A	MKT-MAC08A
INCH DIMS		DO NOT SCALE DRAWING		REV 4
				SHEET 1 of 1